

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6803xxxx4R-G
Typical Mass: 4 mg

| Part name | Weight(mg) | Material name | Ratio(ppm) | CAS number |
|--------------|------------|-----------------|------------|------------|
| Silicon chip | 0.377 | Silicon | 94400 | 7440-21-3 |
| | - | Arsenic | <1 | 7440-38-2 |
| Lead pad | 1.255 | Nickel | 313900 | 7440-02-0 |
| | 0.116 | Silver | 29100 | 7440-22-4 |
| | 0.022 | Gold | 5600 | 7440-57-5 |
| Die attach | 0.026 | Epoxy Resin | 6600 | — |
| | 0.016 | Acrylic Resin | 3900 | — |
| Bonding wire | 0.060 | Gold | 15100 | 7440-57-5 |
| | | | | |
| Resin | 1.649 | Silica | 412200 | 60676-86-0 |
| | 0.167 | Epoxy Resin | 41800 | — |
| | 0.157 | Phenol Resin | 39300 | — |
| | 0.153 | Metal hydroxide | 38200 | — |
| | | | | |

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."